

			PMP9097 REVB BOM		8/20/2013	
Count	RefDes	Value	Description	Size	Part Number	MFR
1	C12	0.01uF	Capacitor, Ceramic, 50V, X7R	603	Std	TDK
1	C1	0.1uF	Capacitor, Ceramic, 25V, X7R	603	Std	TDK
1	C9	5.6pF	Capacitor, Ceramic, 50V, NP0/C0G	603	Std	TDK
1	C10	2700pF	Capacitor, Ceramic, 50V, C0G/NP0	603	Std	Std
2	C100, C7	3.3uF	Capacitor, Ceramic, 50V, X7R, 15%	1210	Std	TDK
1	C4	22uF	Capacitor, Ceramic, 16V, X7R, 15%	1210	C3225X7R1C226M250AC	TDK
1	D2	B1100	Diode, Schottky, 1A, 100V	SMA	B1100	Diodes Inc.
1	L2	22uH	Inductor, SMT, 1.6A, 145 milliohm	0.236"x0.236"	LPS6235-223	Coiltronics
1	JP1	PTC36SAAN	Header, 2-pin, 100mil spacing, (36-pin strip)	0.1" x 2	PTC36SAAN	Sullins
1	R11	10K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R5	18.7K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R7	0	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R8	51.1	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R10	52.3K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R1	76.8K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R3	499K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R2	348K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	J1	ED555/3DS	Terminal Block, 3-pin, 6-A, 3.5mm	0.41" x 0.25"	ED555/3DS	OST
9	TP1-5, TP10, 12, 13, 16	5000	Test Point, Red, Thru Hole Color Keyed	0.1" x 0.1"	5000	Keystone
1	TP14	5001	Test Point, Black, Thru Hole Color Keyed	0.1" x 0.1"	5001	Keystone
1	U1	TPS54160DGQ	IC,DC-DC Converter, 3V-60V, 1.5A	MSOP-10	TPS54160DGQ	TI

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